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Serial No. 09/198,849 MINISTRACTION THE DEVICE MOUNTING L	24 98 OFGS File No. P 1929 - 47 (ETHO) Date 6/27/00
First Inventor 405h:00 bu Kanes The PTO has received:	Last Due Date
□ Patent Application of Pages (including claims & abstract) □ Declaration or □ Designation Sheet □ Drawings Sheet(s)/Figs to □ Priority Document □ Small Entity Declaration □ Assignment & Conveyance Cover Sheet □ Information Disclosure Statement □ PTO-1449 □ Affidavit or Declaration	□ TM Application □ ITU Basis □ Statement of Use □ Extension of Time □ Notice of Appeal □ Brief □ Petition □ Status Request □ Issue Fee □ Certificate of Mailing □ Express Mail No.
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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:

Yoshinobu KANEYAMA

Serial No.: 09/198,849

Filed: November 24, 1998

For: DEVICE MOUNTING METHOD

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New York, New York
Date: June 27, 2000
Group Art Unit: 1725

Examiner: M. Elve

Asst. Commissioner for Patents Washington, D.C. 20231

AMENDMENT

Sir:

In response to the Office Action mailed March 28, 2000, please reconsider the above-identified application amended as follows:

IN THE CLAIMS:

Please amend the claims as follows:

1. (Amended) A [mount] mounting method for joining a device to a substrate using solder [with soldering], characterized in that [joint] the joining of said device and said substrate [through solder] is performed while said device is at least partially submerged in a liquid, wherein said device is at least partially supported by a buoyant force.

2. (Amended) The [mount] mounting method as claimed in claim 1, wherein

01/16/2001 YMIDDLET 0000 the [joint based on] joining of said substrate to said device using said solder is performed while 01 FC:103

108.00 [illtrasonic] a vibration is applied to said [solder through the liquid] device.

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